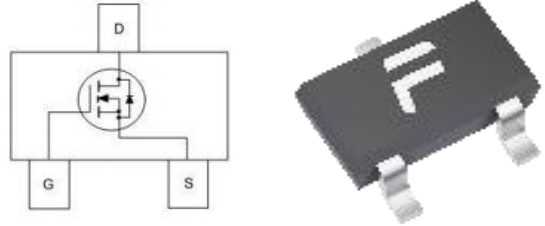


**SOT-23-3L 100V N Channel Enhancement 沟道增强型  
MOS Field Effect Transistor 场效应管**



■ **Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	$BV_{DSS}$	100	V
Gate- Source Voltage 栅极-源极电压	$V_{GS}$	$\pm 20$	V
Drain Current (continuous)漏极电流-连续	$I_D$ (at $T_A = 25^\circ C$ )	2	A
Drain Current (pulsed)漏极电流-脉冲	$I_{DM}$	8	A
Total Device Dissipation 总耗散功率	$P_D$ (at $T_A = 25^\circ C$ )	1300	mW
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	96	$^\circ C/W$
Junction/Storage Temperature 结温/储存温度	$T_J, T_{stg}$	-55~150	$^\circ C$

■ **Device Marking 产品字标**

FS3442=3442

**Electrical Characteristics 电特性**

 (T<sub>A</sub>=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I <sub>D</sub> =250uA, V <sub>GS</sub> =0V)	BV <sub>DSS</sub>	100	—	—	V
Gate Threshold Voltage 栅极开启电压(I <sub>D</sub> =250uA, V <sub>GS</sub> =V <sub>DS</sub> )	V <sub>GS(th)</sub>	1.1	1.8	2.5	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V <sub>GS</sub> =0V, V <sub>DS</sub> =100V)	I <sub>DSS</sub>	—	—	1	uA
Gate Body Leakage 栅极漏电流(V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V)	I <sub>GSS</sub>	—	—	±100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I <sub>D</sub> =2A, V <sub>GS</sub> =10V) (I <sub>D</sub> =1A, V <sub>GS</sub> =4.5V)	R <sub>DS(ON)</sub>	—	250 280	280 310	mΩ
Diode Forward Voltage Drop 内附二极管正向压降(I <sub>SD</sub> =2A, V <sub>GS</sub> =0V)	V <sub>SD</sub>	—	—	1.2	V
Input Capacitance 输入电容 (V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, f=1MHz)	C <sub>ISS</sub>	—	388	—	pF
Common Source Output Capacitance 共源输出电容(V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, f=1MHz)	C <sub>OSS</sub>	—	31	—	pF
Reverse Transfer Capacitance 反馈电容(V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, f=1MHz)	C <sub>RSS</sub>	—	28	—	pF
Total Gate Charge 栅极电荷密度 (V <sub>DS</sub> =50V, I <sub>D</sub> =2A, V <sub>GS</sub> =10V)	Q <sub>g</sub>	—	10	—	nC
Gate Source Charge 栅源电荷密度 (V <sub>DS</sub> =50V, I <sub>D</sub> =2A, V <sub>GS</sub> =10V)	Q <sub>gs</sub>	—	2	—	nC
Gate Drain Charge 栅漏电荷密度 (V <sub>DS</sub> =50V, I <sub>D</sub> =2A, V <sub>GS</sub> =10V)	Q <sub>gd</sub>	—	2	—	nC
Turn-ON Delay Time 开启延迟时间 (V <sub>DS</sub> =50V I <sub>D</sub> =1.5A, R <sub>GEN</sub> =1Ω, V <sub>GS</sub> =10V)	t <sub>d(on)</sub>	—	5	—	ns
Turn-ON Rise Time 开启上升时间 (V <sub>DS</sub> =50V I <sub>D</sub> =1.5A, R <sub>GEN</sub> =1Ω, V <sub>GS</sub> =10V)	t <sub>r</sub>	—	18	—	ns
Turn-OFF Delay Time 关断延迟时间 (V <sub>DS</sub> =50V I <sub>D</sub> =1.5A, R <sub>GEN</sub> =1Ω, V <sub>GS</sub> =10V)	t <sub>d(off)</sub>	—	13	—	ns
Turn-OFF Fall Time 关断下降时间 (V <sub>DS</sub> =50V I <sub>D</sub> =1.5A, R <sub>GEN</sub> =1Ω, V <sub>GS</sub> =10V)	t <sub>f</sub>	—	28	—	ns

■ Typical Characteristic Curve 典型特性曲线

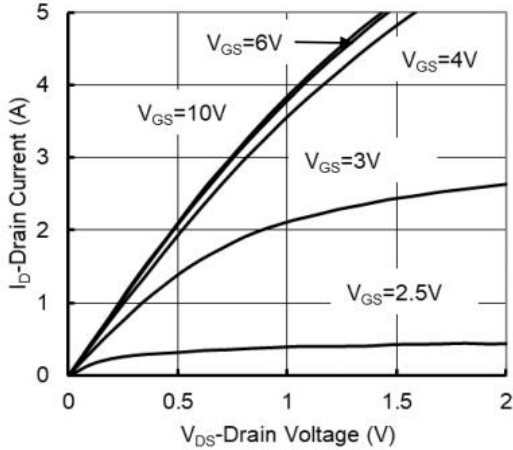


Figure 1: Output Characteristics

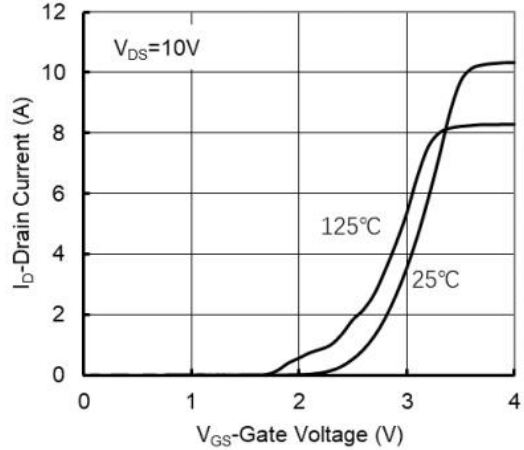


Figure 2: Transfer Characteristics

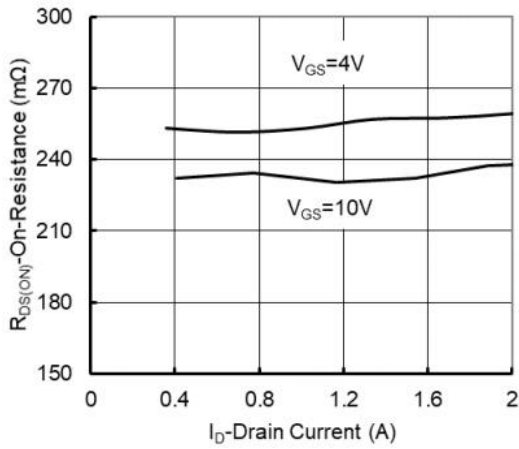


Figure 3: On-Resistance vs. Drain Current

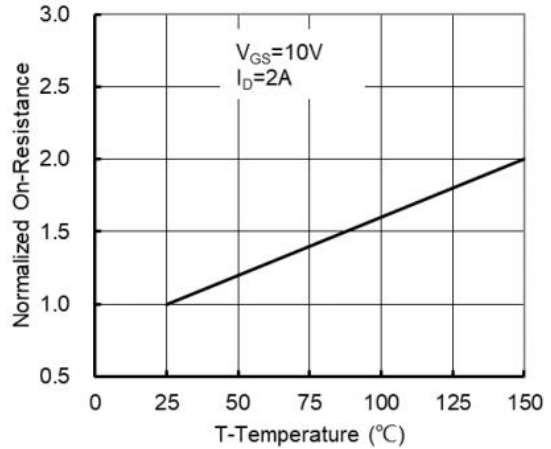


Figure 4: On-Resistance vs. Temperature

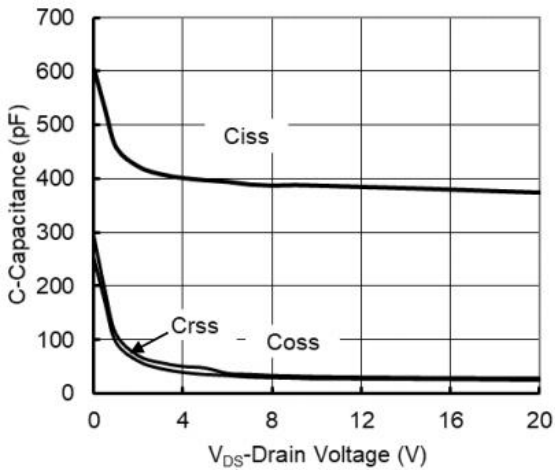


Figure 5: Capacitance Characteristics

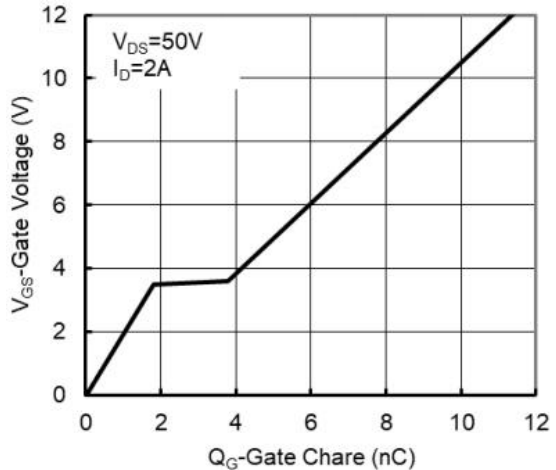


Figure 6: Gate-Charge Characteristics

■ Typical Characteristic Curve 典型特性曲线

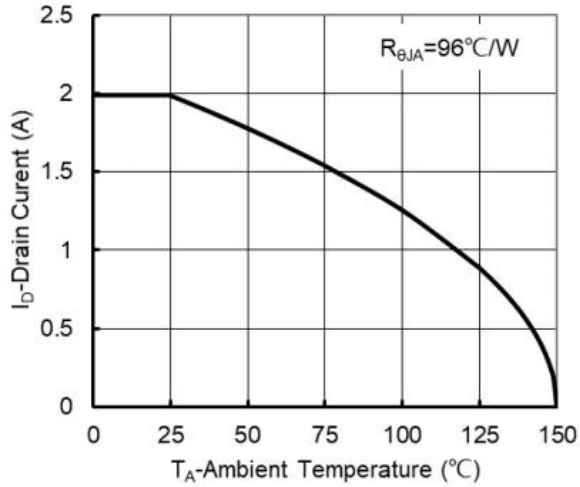


Figure 7: Drain Current vs. Temperature

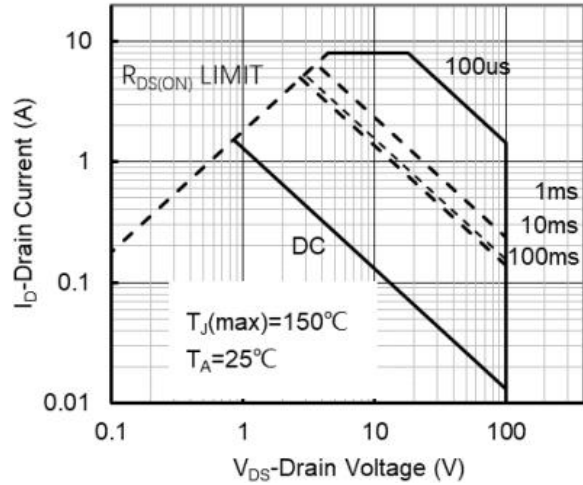


Figure 8: Safe Operating Area

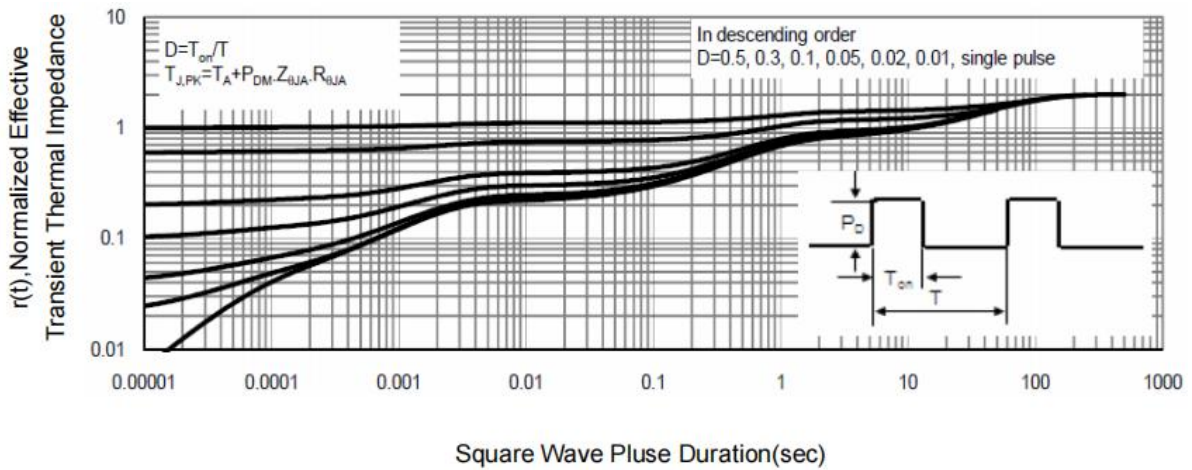
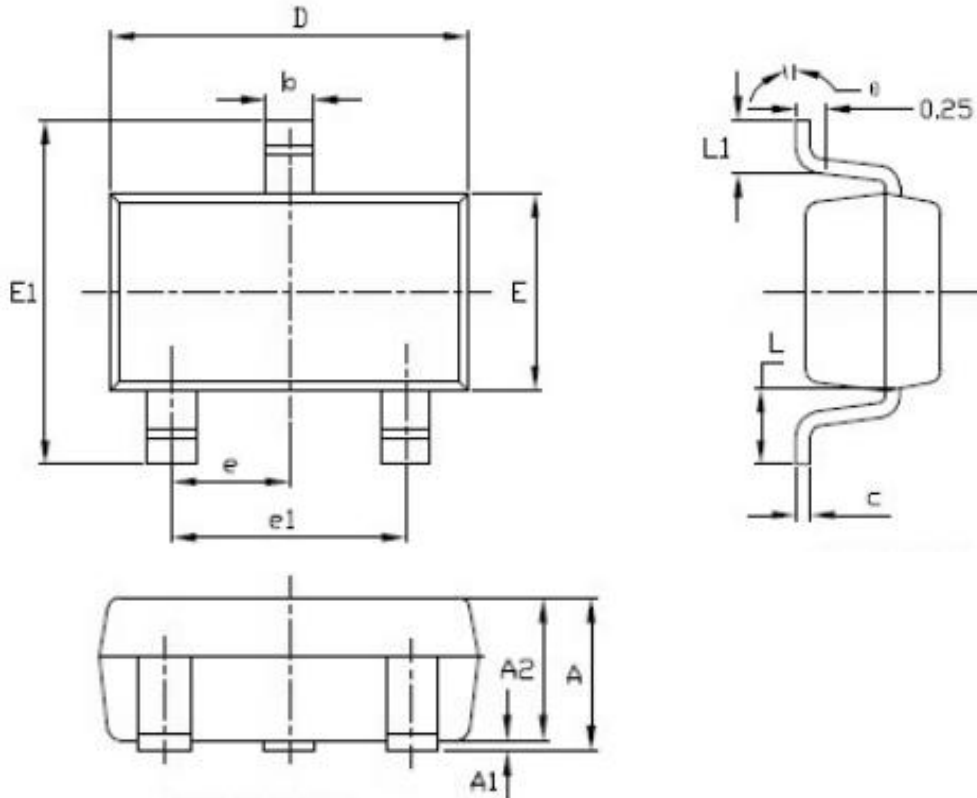


Figure 9: Transient Thermal Response Curve

■ Dimension 外形封装尺寸



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.600REF		0.024REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°